... 09/916197

Cgc





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Hui et al.

Patent No.: 6,781,248 B2

Issued: August 24, 2004

For: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Attorney Docket No.: 2269-4712US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 26, 2006 Date

Erika Gandre
Name (Type/Print)

Certificate

FEB 0 2 2006

of Correction

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT OFFICE MISTAKES (37 C.F.R. § 1.322)

Attn.: Certificate of Corrections Branch Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

It is noted that several errors appear in this patent of a typographical nature. These errors are due to mistakes in printing on the part of the U.S. Patent and Trademark Office, and occurred through no fault of the Applicants. A certificate of correction in the form attached hereto is requested.

Patent No. 6,781,248 B2

Please send the Certificate to:

Name:

Brick G. Power

Address:

TraskBritt

P.O. Box 2550

Salt Lake City, Utah 84110

Attached hereto in duplicate is Form PTO/SB/44 with at least one copy being suitable for printing.

Respectfully submitted,

Brick G. Power

Registration No. 38,581 Attorney for Applicant(s)

TRASKBRITT P.O. Box 2550

Salt Lake City, Utah 84110-2550

Telephone: 801-532-1922

Date: January 26, 2006

BGP/csw

Enclosures: PTO/SB/44 in duplicate

Document in ProLaw

CERTIFICATE OF CORRECTION

PATENT NO

6,781,248 B2

Page 1 of 5

DATED

August 24, 2004

INVENTOR(S):

Chong Chin Hui; Lee Kian Chai; and Jason Pittam

It is certified that errors appear in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

In the drawings:

In FIG. 3:

switch reference numerals "24" and "34"

In FIG. 4:

add reference numeral --20-- and appropriate lead

line therefor

In FIG. 4A:

insert two lead lines extending from --40-- toward

the depicted conductive elements

In the specification:

COLUMN 2, LINES 5-6,

delete "[as the contacts pads]" change "thereof" to --thereof.--

COLUMN 2, LINE 21, COLUMN 4, LINE 30,

change "production" to --introduction--

COLUMN 4, LINE 50,

before "backside" change "the" to --a--

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PATENT NO. <u>6,781,248 B2</u>

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INVENTOR(S):

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In the claims:

```
CLAIM 43, COLUMN 11, LINE 60,
                                     delete "sad"
CLAIM 45, COLUMN 12, LINE 1,
                                     delete "said"
CLAIM 62, COLUMN 12, LINE 67,
                                     change "& the" to --the--
CLAIM 66, COLUMN 13, LINE 16,
                                     delete "so"
                                     delete "sa"
CLAIM 67, COLUMN 13, LINE 21,
CLAIM 69, COLUMN 13, LINE 30,
                                     delete "so"
CLAIM 87, COLUMN 14, LINE 47,
                                     change "s*the" to --the--
                                     delete "exposed to"
CLAIM 97, COLUMN 15, LINE 27,
CLAIM 97, COLUMN 15, LINE 28,
                                     delete "s %"
CLAIM 99, COLUMN 15, LINE 35,
                                     delete "so"
CLAIM 110, COLUMN 16, LINE 29,
                                     delete "so"
                                     change "clement" to --element--
CLAIM 110, COLUMN 16, LINE 30,
CLAIM 111, COLUMN 16, LINE 35.
                                     delete "so"
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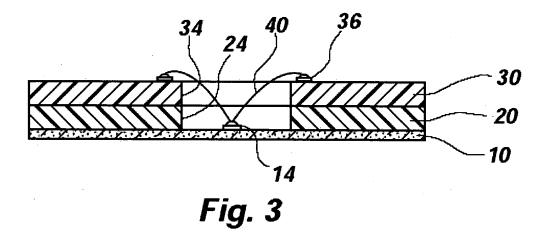
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Please replace FIG. 3 with the following:



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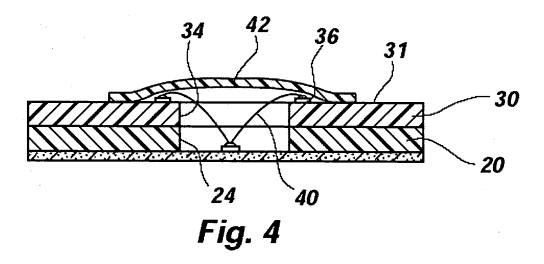
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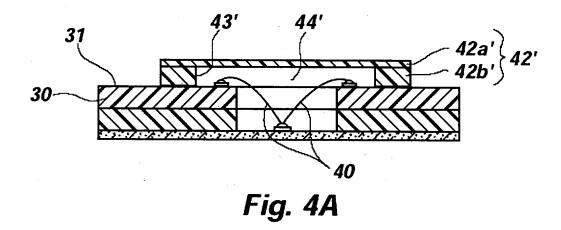
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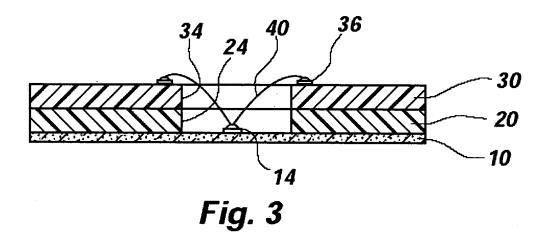
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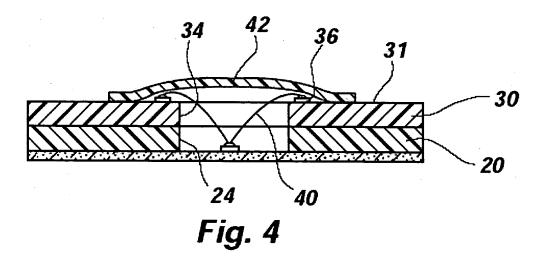
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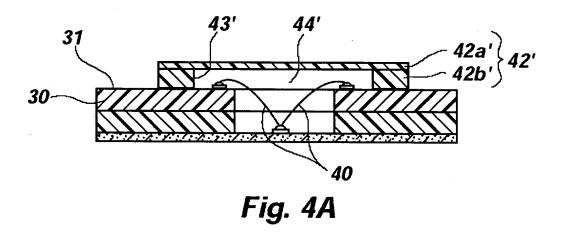
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